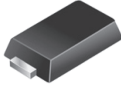


New eSMP™ Surface Mount Package Series with Unique Wide Bottom Plate Designs and Space-Saving Footprints

SMP



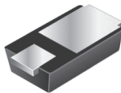
Rectifiers
TVS
(3.8 x 2 x 1) mm

SMPC



Rectifiers
TVS
(6.7 x 4.8 x 1.1) mm

MicroSMP



Rectifiers
TVS
(2.5 x 1.3 x 0.68) mm

Vishay General Semiconductor developed the new eSMP™ high current density power efficiency surface mount package series with unique designs for better thermal performance and reliability.

FEATURES

- Space saving miniature packages:
SMP (3.8 x 2 x 1) mm
SMPC (6.7 x 4.8 x 1.1) mm
MicroSMP (2.5 x 1.3 x 0.65) mm
- Special wide bottom plate design:
Greater heat dissipation than other packages of similar sizes
- Low device height
- Low thermal resistance
- AEC-Q101 qualified
- Available for Schottky, ultrafast and standard rectifiers

APPLICATIONS

Efficient and space saving package choice for telecom, automotive, computer, industrial and mobile consumer electronic applications

	$R_{\theta JL}$
MicroSMP	30 °C/W
SMP	15 °C/W
SMPC	3 °C/W